



TECHNICAL REPORT

**Semiconductor die products –
Part 8: EXPRESS model schema for data exchange**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE

U

CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references.....	6
3 Terms and definitions	7
4 General	7
5 Data exchange	7
Annex A (normative) EXPRESS model schema	8
Annex B (informative) STEP physical file example	25

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

Part 8: EXPRESS model schema for data exchange

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-8, which is a technical report, has been prepared by subcommittee 47: Semiconductor devices.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/1927/DTR	47/1952/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62258 series, under the general title *Semiconductor die products*, can be found on the IEC website. Further parts may be added as required.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organisations that helped prepare this document included the ESPRIT ENCAST project, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 8: EXPRESS model schema for data exchange

1 Scope

This part of IEC 62258, which is a technical report, has been developed to facilitate the production, supply and use of semiconductor die products, including

- wafers,
- singulated bare die,
- die and wafers with attached connection structures,
- minimally or partially encapsulated die and wafers.

This Technical Report contains an EXPRESS model schema that describes the elements needed for data exchange and that will allow the implementation of the requirements of the IEC 62258-1, IEC 62258-5 and IEC 62258-6 standards, as well as providing an exchange structure that is complementary to those defined in IEC 62258-2. It is also complementary to and compatible with the questionnaire in IEC 62258-4.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary*

IEC 62258-1, *Semiconductor die products – Part 1: Requirements for procurement and use*

IEC 62258-2, *Semiconductor die products – Part 2: Exchange data formats*

IEC/TR 62258-4, *Semiconductor die products – Part 4: Questionnaire for die users and suppliers*

IEC 62258-5, *Semiconductor die products – Part 5: Requirements for information concerning electrical simulation*

IEC 62258-6, *Semiconductor die products – Part 6: Requirements for information concerning thermal simulation*

ISO 10303-11:2004, *Industrial automation systems and integration – Product data representation and exchange – Part 11: Description methods: The EXPRESS language reference manual*

ISO 10303-21:2002, *Industrial automation systems and integration – Product data representation and exchange – Part 21: Implementation methods: Clear text encoding of the exchange structure*